



1200V N-CHANNEL SILICON CARBIDE POWER MOSFET

Product Summary

BV _{DSS}	RDS(ON) Max	I _D T _C = +25°C		
1200V	43mΩ @ V _G S = 15V	70.5A		

Description and Applications

This SiC MOSFET is designed to minimize the on-state resistance yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

- EV high-power DC-DC converters
- · EV charging systems
- AC-DC traction inverters
- Solar inverters
- Automotive motor drivers

Mechanical Data

- Package: TO247-4
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0

AEC-Q101 qualified, PPAP capable, and manufactured in

https://www.diodes.com/quality/product-definitions/

Terminal Connections: See Diagram

IATF 16949 certified facilities.

- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 6.6 grams (Approximate)

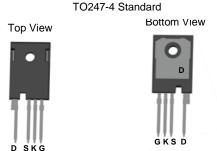
Features and Benefits

Low On-Resistance

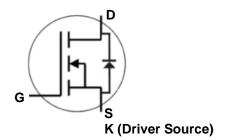
Low Input Capacitance

High BVDSS Rating for Power Application

Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
Halogen and Antimony Free. "Green" Device (Note 3)
The DMWSH120H43SM4Q is suitable for automotive
applications requiring specific change control; this part is



Pin Configuration



Internal Schematic

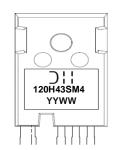
Ordering Information (Note 4)

Ondonable Boot Neuroben	Deekere	Packing		
Orderable Part Number	Package	Qty.	Carrier	
DMWSH120H43SM4Q	TO247-4 Standard	30 Pieces	Tube	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	1200	V
Gate-Source Voltage		Vgss	+19/-8	V
Gate-Source Voltage (Recommended Operating Values)		Vgss	+15/-4	V
Continuous Drain Current (Notes 5, 6)	T _C = +25°C T _C = +100°C	lo	70.5 49.8	А
Continuous Diode Forward Current (Note 5)	Is	63	А	
Pulsed Source Current (Pulse Width tp Limited by TJ Max) (Note 5)		lsм	151	Α
Pulsed Drain Current (Pulse Width tp Limited by T _{J Max}) (Note 5)		I _{DM}	151	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _C = +25°C	Pp	320	W
Total Fower Dissipation (Note 3)	Tc = +100°C	PD	160	
Thermal Resistance, Junction to Ambient (Note 7)		R _{0JA}	29.4	°C/W
Thermal Resistance, Junction to Case (Note 5)		Rejc	0.47	*C/VV
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

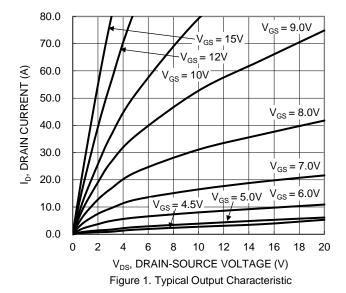
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	1200	_	_	V	VGS = 0, ID = 100µA	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	50	μA	V _{DS} = 1200V, V _{GS} = 0	
Gate-Source Leakage	Igss	1		±250	nA	V _G S = +15/-4V, V _D S = 0	
ON CHARACTERISTICS (Note 8)	ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	Vgs(TH)	1.8	2.5	3.6	V	V _{DS} = V _{GS} , I _D = 11.5mA	
Static Drain-Source On-Resistance	R _{DS(ON)}		33	43	mΩ	V _{GS} = 15V, I _D = 40A	
Diode Forward Voltage	VsD		4.0	_	V	V _G S = -4V, I _S = 20A	
Transconductance	gfs		8.9	_	S	VDS = 20V, ID = 40A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss		2204	_		V _G S = 0, V _D S = 1000V V _A C = 25mV, f = 1MHz	
Output Capacitance	Coss		106	_	pF		
Reverse Transfer Capacitance	Crss	1	6.6	_			
Coss Stored Energy	E _{oss}	_	65	_	μJ		
Turn-On Switching Energy (Body Diode Forward)	Eon		581	_	n I	V _{GS} = -4V/+15V, V _{DS} = 800V	
Turn-Off Switching Energy (Body Diode Forward)	Eoff	_	245	_	μJ	$R_g = 5\Omega$, $I_D = 40A$, $L = 157\mu H$	
Gate Resistance	R_g		1.4	_	Ω	V _{AC} = 100mV, f = 1MHz	
Total Gate Charge	Q_g		114	_		V _{GS} = -4V/+15V, V _{DS} = 800V I _D = 40A	
Gate-Source Charge	Qgs	_	40.9	_	nC		
Gate-Drain Charge	Q_{gd}		38.7	_			
Turn-On Delay Time	t _{D(ON)}	1	15.8	_		$V_{GS} = -4V/+15V$, $V_{DD} = 800V$ $R_g = 5\Omega$, $I_D = 40A$ Inductive Load	
Turn-On Rise Time	t _R	I	37.3	_	ns		
Turn-Off Delay Time	tD(OFF)	I	31.3	_	115		
Turn-Off Fall Time	tF	1	8.9	_			
Body Diode Reverse-Recovery Time	t _{RR}	I	21.4	_	ns	V _G S = -4V, V _D S = 800V I _D = 40A, di/dt = 1500A/µs	
Body Diode Reverse-Recovery Charge	Q _{RR}	I	208	_	nC		
Body Diode Reverse-Recovery Current	IRRM		16.1	_	A ID = 40A, α/αι = 1500A/μs		

Notes:

- 5. Device mounted on an infinite heatsink.
- Drain current limited by maximum junction temperature.
 Device mounted on FR-4 substrate PC board, 2oz. copper, with minimum recommended pad layout.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to production testing.





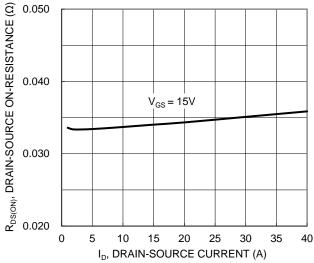


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

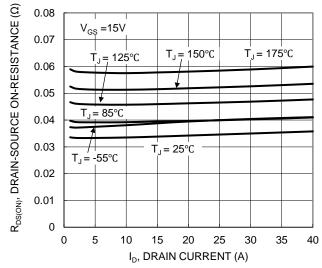
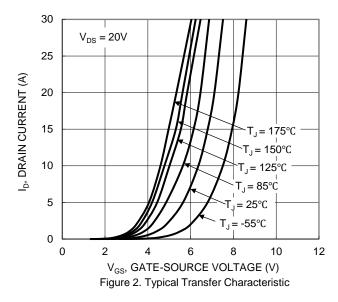


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



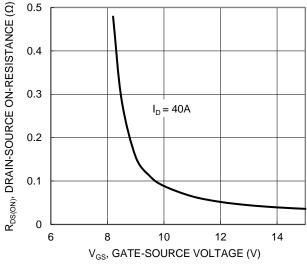


Figure 4. Typical Transfer Characteristic

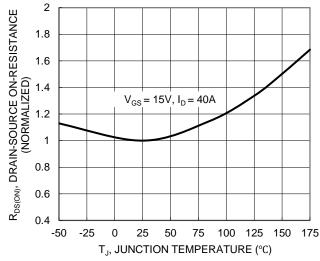


Figure 6. On-Resistance Variation with Junction Temperature





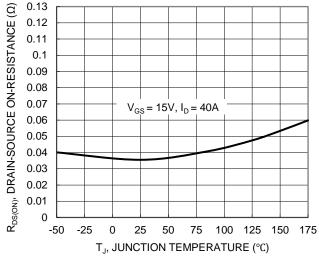


Figure 7. On-Resistance Variation with Junction Temperature

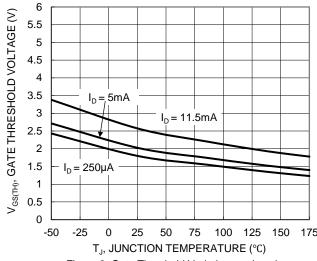


Figure 8. Gate Threshold Variation vs. Junction Temperature

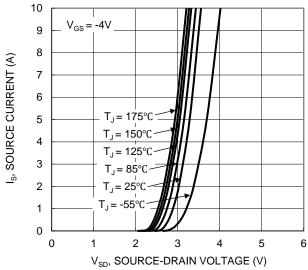
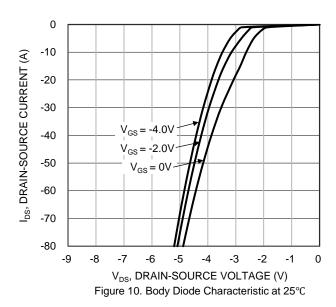
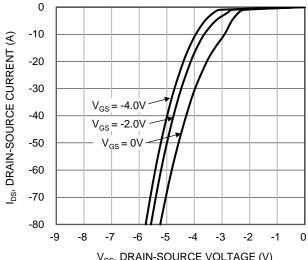
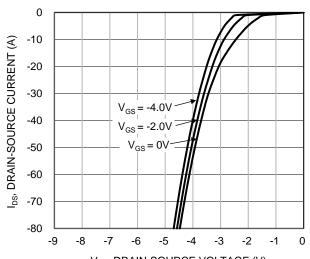


Figure 9. Diode Forward Voltage vs. Current





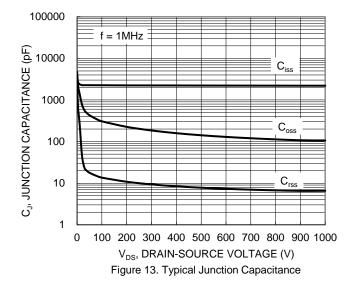
V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 11. Body Diode Characteristic at -55°C

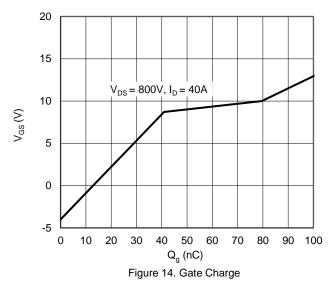


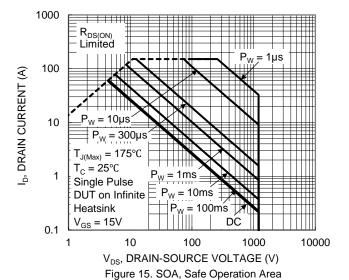
V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 12. Body Diode Characteristic at 175°C











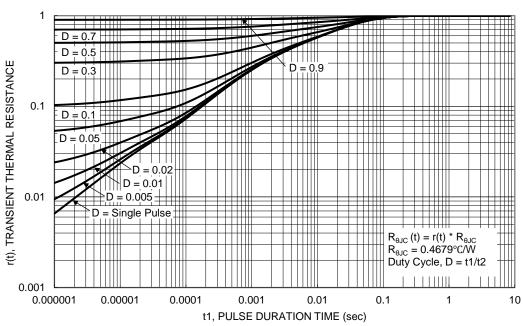


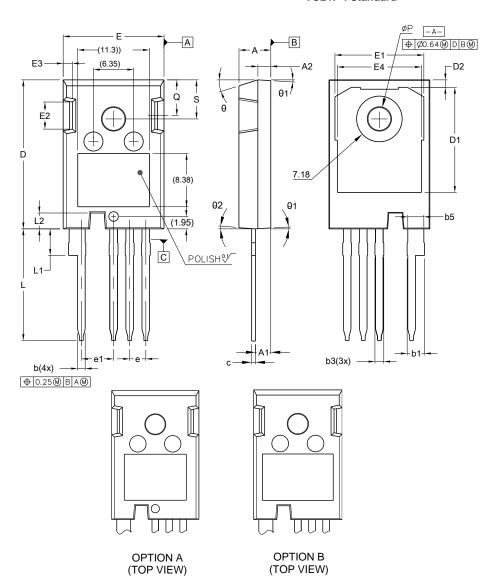
Figure 16. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO247-4 Standard



TO247-4 Standard					
Dim	Min	Max			
Α	4.83	5.21			
A1	2.29	2.54			
A2	1.91	2.16			
b	1.07	1.33			
b1	2.39	2.94			
b3	1.07	1.60			
b5	2.39	2.69			
С	0.55	0.68			
D	23.30	23.60			
D1	16.25	17.65			
D2	0.95	1.25			
Е	15.75	16.30			
E1	13.10	14.15			
E2	3.68	5.10			
E3	1.00	1.90			
E4	12.38	13.43			
е	2.54 BSC				
e1	5.08 BSC				
L L1	17.31	17.82			
L1	3.97	4.37			
L2	2.35	2.65			
ØΡ	3.51	3.65			
Q	5.49	6.00			
S	6.04	6.30			
θ	6.04 6.30 17.5°- 20° REF				
θ1	3.5°- 5° REF				
θ2	4°- 5° REF				
All Dimensions in mm					



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